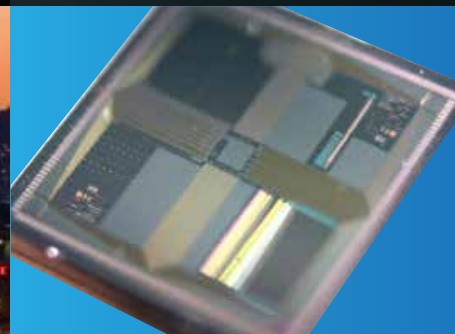


2014 Circuit Device Interaction Special Focus Session

at the 2014 IEEE International Electron Devices Meeting

Hilton San Francisco
Union Square
December 15-17, 2014



Tuesday, December 16 - 2:15 - 5:30

Session 18: Analog & Mixed Signal Circuit Device Interaction

Continental Ballroom 5

- **18.1 “Device Aware High-Speed Transceiver Design in Planar and FinFET Technologies”**
K. Chang, J. Savog, et. al., Xilinx Inc.
- **18.2 “Mismatch in High-K Metal Gate Process Analog Design”**
A. Woo, et. al., Broadcom Corporation
- **18.3 “Challenges of Analog and I/O Scaling in 10nm SoC Technology and Beyond”**
A. Wei, et.al., GLOBALFOUNDRIES
- **18.4 “Technology Pathfinders for Low Cost and Highy Integrated RF Front End Modules”**
C. Raynaud, CEA-LETI
- **18.5 “Digitally-Intensive RF Transceivers in Highly Scaled CMOS”**
C.M. Hung, MediaTek Inc.
- **18.6 “Circuit and Device Interactions for 3D Integration Using Inductive Coupling”**
T. Kuroda, Keio University

Technical Program

IEDM’s technical program consists of more than 200 papers from the world’s leading experts from industry, government & academia, covering the following topics:

- Circuit & Process Interaction
- Non-Boolean Computing
- Bio-Sensors & BioMEMS
- 2D Electronics
- Energy Harvesting
- Spintronics
- Multiferroics
- Power Devices
- Sensors
- Magnetics

IEDM 2014 Highlights

Plenary Presentations

“SiC MOSFET Development for Industrial Markets”

“Are 3D Atomic Printers Around the Corner? “

“Research into ADAS with Driving Intelligence for Future Innovation”

Evening Panel Discussion

“60 Years of IEDM & Counting”

IEDM Luncheon Speaker

T.J. Rodgers
Founder/President/CEO,
Cypress Semiconductor

Entrepreneurs Luncheon Speaker

Kathryn Kronen
Former President/CEO,
Jasper Design Automation



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